CLAIMS

1. An adhesive film comprising:

a base material layer;

an adhesive resin layer (A) provided on a first surface side of the base material layer; and

an adhesive resin layer (B) provided on a second surface side of the base material layer and of which an adhesive force is reduced by an external stimulus,

wherein, when a mass of the adhesive film after being heated and dried at 130°C for 30 minutes is defined as W_1 and a mass of the adhesive film after the heated and dried adhesive film is left for 24 hours at 25°C under an atmosphere of 50% RH to absorb water is defined as W_2, an average water absorption rate indicated by $100 \times (W_2-W_1)/W_1$ is 0.65% by mass or less.

2. The adhesive film according to claim 1,

wherein the base material layer includes a uniaxially stretched or biaxially stretched polyester film.

3. The adhesive film according to claim 1 or 2,

wherein the adhesive force of the adhesive resin layer (B) is reduced upon being heated at a temperature exceeding 180°C.

4. The adhesive film according to claim 3,

wherein the adhesive resin layer (B) includes at least one selected from a gas generating component and heat-expandable microspheres.

5. The adhesive film according to any one of claims 1 to 4,

wherein a content of at least one selected from a gas generating component and heat-expandable microspheres in the adhesive resin layer (A) is 0.1% by mass or less when the entire adhesive resin layer (A) is 100% by mass.

6. The adhesive film according to any one of claims 1 to 5,

wherein the adhesive resin layer (A) includes a (meth)acrylic-based adhesive resin.

7. Use of the adhesive film according to any one of claims 1 to 6,

for temporarily fixing an electronic component when the electronic component is sealed by a sealing material in an electronic device manufacturing process.

8. A method for manufacturing an electronic device, the method comprising at least:

a step (1) of preparing a structure provided with the adhesive film according to any one of claims 1 to 6, an electronic component attached to the adhesive resin layer (A) of the adhesive film, and a support substrate attached to the adhesive resin layer (B) of the adhesive film;

a step (2) of sealing the electronic component with a sealing material;

a step (3) of peeling the support substrate from the structure by reducing an adhesive force of the adhesive resin layer (B) by applying an external stimulus; and

a step (4) of peeling the adhesive film from the electronic component.

9. The method for manufacturing an electronic device according to claim 8,

wherein the sealing material is an epoxy resin-based sealing material.